

Title (en)
PROCESS AND MANUFACTURING TOOL ARCHITECTURE FOR USE IN THE MANUFACTURE OF ONE OR MORE METALLIZATION LEVELS ON A WORKPIECE

Title (de)
VERFAHREN UND ANORDNUNG EINER HERSTELLUNGSVORRICHTUNG ZUR VERWENDUNG IN DER HERSTELLUNG EINES ODER MEHRERER METALLISIERUNGSNIVEAUS AUF EINEM WERKSTÜCK

Title (fr)
OUTIL SERVANT A FABRIQUER UN OU PLUSIEURS NIVEAUX DE METALLISATION SUR UN COMPOSANT A SEMICONDUCTEUR ET PROCEDE CORRESPONDANT

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Application
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- US 12823898 A 19980803

Abstract (en)
[origin: WO9959190A2] A semiconductor manufacturing tool configuration and corresponding process for applying one or more levels of interconnect metallization to a generally planar dielectric surface of a semiconductor workpiece with a minimal number of workpiece transfer operations between the tool sets is disclosed.

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